AT A GLANCE

High power o-band InP BH DFB

Features

• DFB plus SOA approach
• Optional integration of monitor diode
• p-side up or flip-chip configuration
• integrated taper for low loss optical coupling
• 9° output facet
• on request precise alignment structures for lateral & vertical positioning
• flexible adaptation of devices corresponding to customer’s applications: e.g. center wavelength, coating against n=1.5...

Applications

• Telecom/Datacom
• Sensors
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<table>
<thead>
<tr>
<th>Parameters</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
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<tbody>
<tr>
<td>Side mode suppression ratio</td>
<td>40</td>
<td></td>
<td></td>
<td>dB</td>
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<tr>
<td>Relative intensity noise</td>
<td>-155</td>
<td>-145</td>
<td></td>
<td>dB/Hz</td>
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<tr>
<td>Optical line width (Lorentzian)</td>
<td>1.0</td>
<td></td>
<td></td>
<td>MHz</td>
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<td>Far field angle (FWHM)</td>
<td>16x22</td>
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